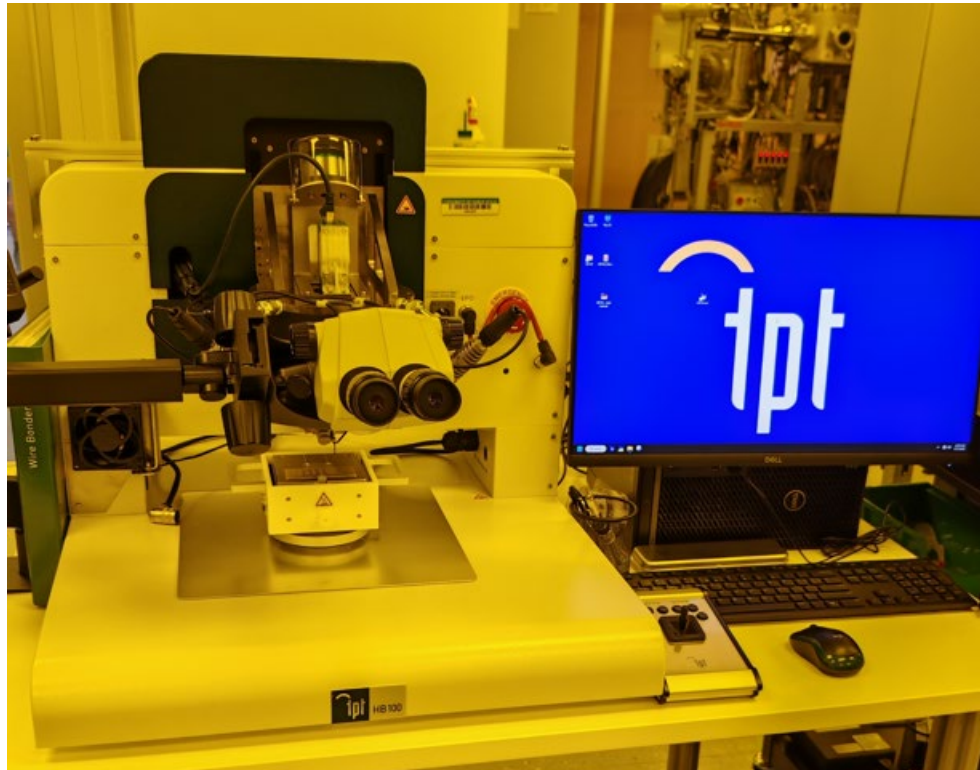


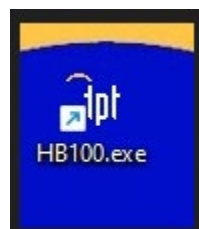
TPT HB100 Wire Bonder

07/29/2026



Operation Steps:

1. Turn on the power switch on the back of the wirebonder main console.
2. Open the software and system initialize:



Bond Program

Inspection

Machine Settings

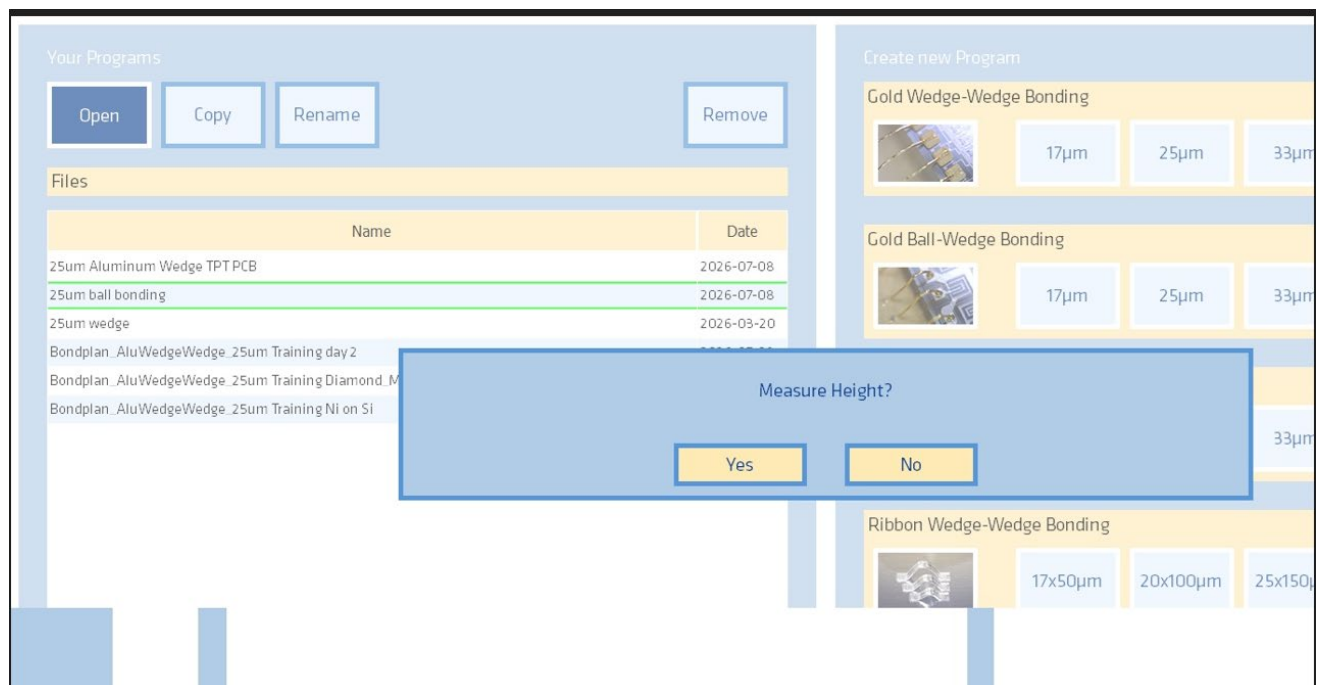
3. Click “Bond Program”

4. Choose the program eg: 1. for wedge bond setup “25um Aluminum TPT PCB” 2. for ball bond setup “25um ball bonding”

For wedge bonding, unplug the red EFO cable from Bond Head if not unplugged.



5. Click “Open”. Click “yes” for Measure Height



6. Follow the instruction on the upper right line: Press “Bond” button to move to Measure Height Position.

Bond Program - 25um Aluminum TPT PCB

Add Chip

Remove Package

Copy Package

Move to Position

Manual Wire

Single Wire

Bond Package

Next Package

Press **"Bond"** Button to move to Measure Height Position.

Auto Teach OFF

Ready

7. Use the joystick to move the lines to the measure height point which is shown in the lower right pic. Then press “Bond” button.

Close Program

Inspection

Machine Settings

Vision System

Teach Offset

Load Package

Bond Off

EFO

US

Clamp

50 0

Parameters

Cameras

Bond Plan

Settings

49 °C

Bond Program - 25um ball bonding

Add Chip

Remove Package

Copy Package

Move to Position

Manual Wire

Single Wire

Bond Package

Next Package

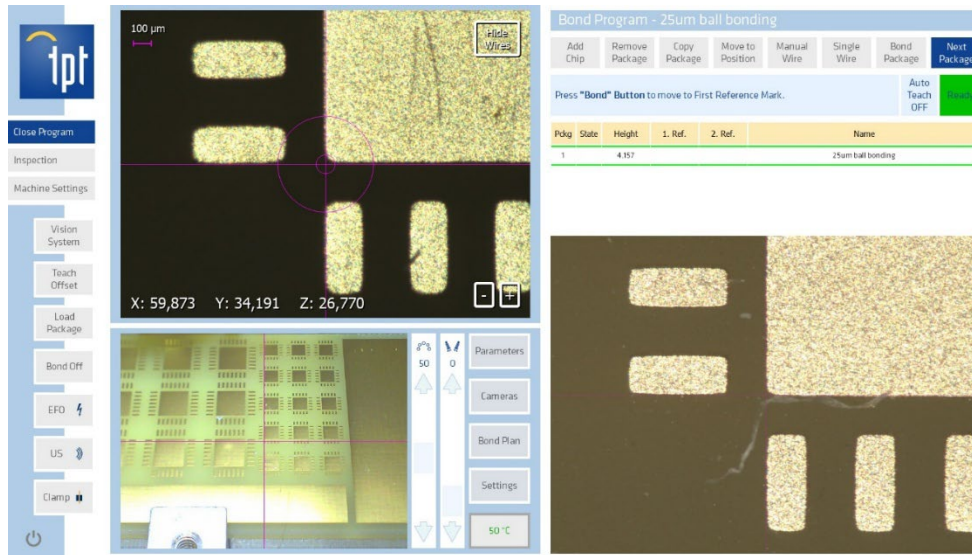
Move Crosshairs to Bond Pad and press "Bond" Button to measure Height.

Auto Teach OFF

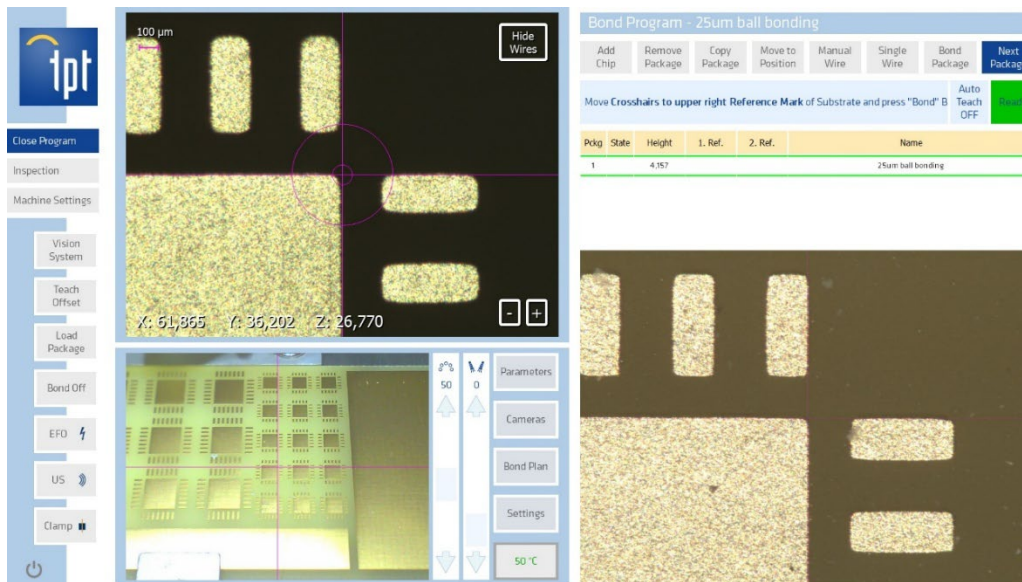
Ready

Pckg	State	Height	1. Ref.	2. Ref.	Name
1		4,158			25um ball bonding

8. Follow instructions for 4 reference marks: use joystick to move the lines to the 1st reference mark as shown in lower right pic.



9. 2nd reference mark: use joystick to move the lines to the 2nd reference mark as shown in lower right pic.



10. Start bonding: choose “continue package”

Bond Program - 25um ball bonding

Add Wire Remove Wire Copy Wire Move to Position Manual Wire Single Wire **Continue Package** Next Package

Bond - "Bond" Button

Auto Teach OFF **Ready**

Pkg	State	Height	1. Ref.	2. Ref.	Name
1		4,157			25um ball bonding

Chip	Base	Height	1. Ref.	2. Ref.	Name
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Wire	State	Length	Loop Height	1. Bond	Loop	2. Bond	Tail	Chip	Comment
1	B	426	600	1	1	2	1	P>P	
2		431	600	1	1	2	1	P>P	
3		430	600	1	1	2	1	P>P	
4		437	600	1	1	2	1	P>P	
5		437	600	1	1	2	1	P>P	

Wires: 5 Bond Counter: 159

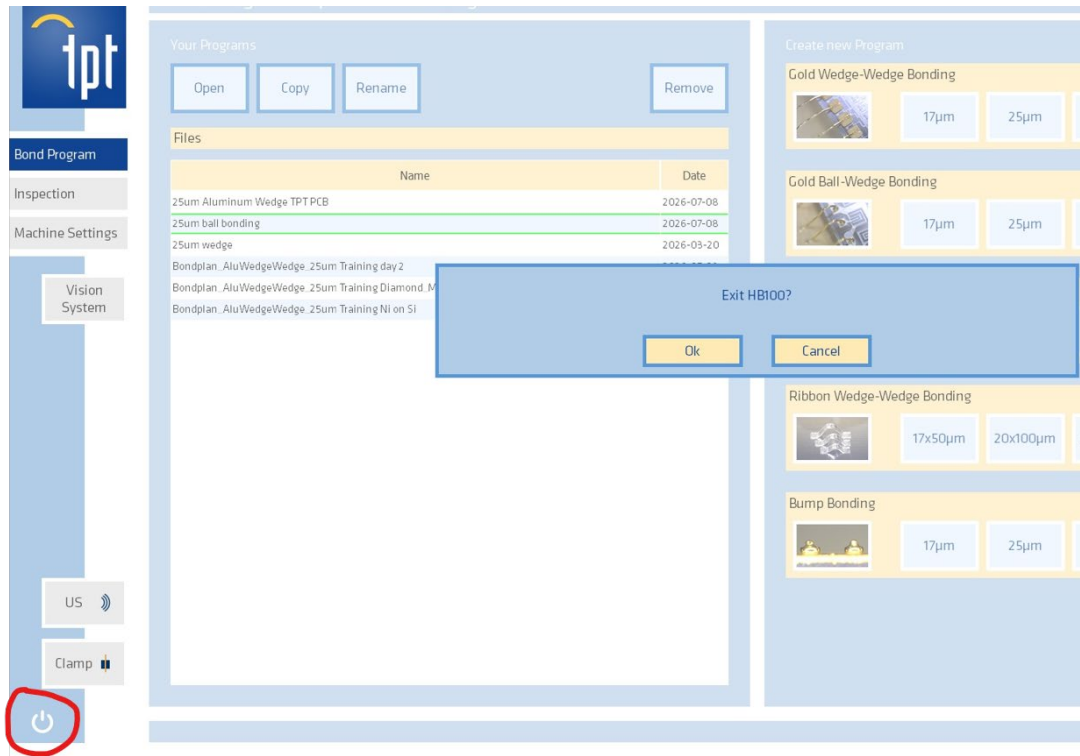
11. All bonds are done and verify them through microscope.

12. Close the program:

Close Bond Program?

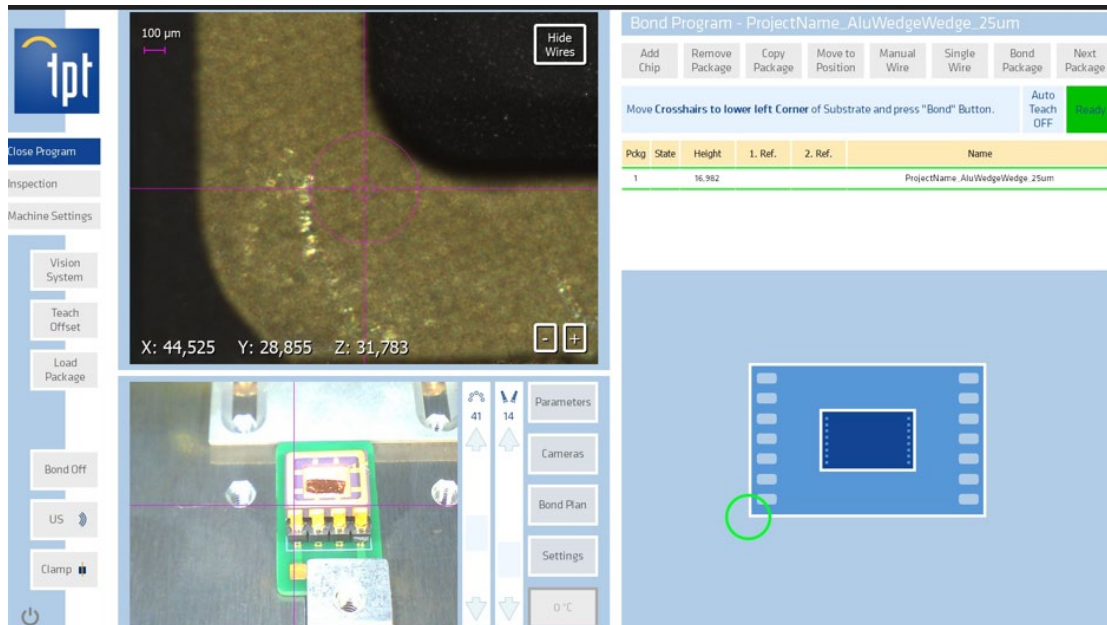
Ok Cancel

13. Exit HB100 and Power off back switch.



For Nonstandard sample (different heights at two bond pad areas):

1. After choosing program, move the cross to the edge of your sample to measure the 1st height.



2. Click “Add Chip” to follow onscreen instruction to add 2nd pad position for height measurement.

